

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

**1. (currently amended):** A heat-peelable double-faced pressure-sensitive adhesive sheet consisting essentially of ~~which comprises~~ a substrate (a), a heat-peelable pressure-sensitive adhesive layer (b) formed on one side of the substrate (a) and containing heat-expandable microspheres, and a pressure-sensitive adhesive layer (c) formed on the other side of the substrate (a), wherein the heat-peelable pressure-sensitive adhesive layer (b) and the substrate (a) are peelable from each other by heating.

**2. (original):** The heat-peelable double-faced pressure-sensitive adhesive sheet according to claim 1, which further comprises a pressure-sensitive adhesive layer (d) superposed on the heat-peelable pressure-sensitive adhesive layer (b) on its side opposite to the substrate (a).

**3. (original):** The heat-peelable double-faced pressure-sensitive adhesive sheet according to claim 2, wherein the pressure-sensitive adhesive layer (d) comprises at least one viscoelastic material selected from the group consisting of a pressure-sensitive adhesive, a radiation-curable pressure-sensitive adhesive, a thermoplastic resin, and a thermosetting resin.

**4. (original):** The heat-peelable double-faced pressure-sensitive adhesive sheet according to any one of claims 1 to 3, wherein the pressure-sensitive adhesive layer (c) comprises at least one viscoelastic material selected from the group consisting of a pressure-

sensitive adhesive, a radiation-curable pressure-sensitive adhesive, a thermosetting resin, and a heat-peelable pressure-sensitive adhesive.

**5. (original):** The heat-peelable double-faced pressure-sensitive adhesive sheet according to any one of claims 1 to 3, wherein the gel content of the pressure-sensitive adhesive layer (c) (after a heat treatment or radiation exposure treatment) is 90% or higher.

**6. (original):** The heat-peelable double-faced pressure-sensitive adhesive sheet according to any one of claims 1 to 3, wherein the pressure-sensitive adhesive constituting the heat-peelable pressure-sensitive adhesive layer (b) is a radiation-curable pressure-sensitive adhesive.

**7. (original):** The heat-peelable double-faced pressure-sensitive adhesive sheet according to any one of claims 1 to 3, wherein that side of the substrate (a) which faces the heat-peelable pressure-sensitive adhesive layer (b) has undergone a releasability-imparting treatment.

**8. (withdrawn):** A method of processing an adherend using the heat-peelable double-faced pressure-sensitive adhesive sheet according to any one of claims 1 to 3, which comprises adhering the adherend to the surface of the pressure-sensitive adhesive layer (c) in the heat-peelable double-faced pressure-sensitive adhesive sheet, adhering a reinforcing plate to the surface of the heat-peelable pressure-sensitive adhesive layer (b) or pressure-sensitive adhesive layer (d), processing the adherend, subsequently causing separation at the interface between the heat-peelable pressure-sensitive adhesive layer (b) and the substrate (a) by heating, separating the processed adherend from the reinforcing plate together with, adherent thereto, the substrate

(a) having the pressure-sensitive adhesive layer (c), and further separating the processed adherend from the substrate (a) having the pressure-sensitive adhesive layer (c).

9. **(withdrawn):** The method of processing an adherend according to claim 8, which comprises adhering the adherend to the surface of the pressure-sensitive adhesive layer (c) in the heat-peelable double-faced pressure-sensitive adhesive sheet, adhering a reinforcing plate to the surface of the heat-peelable pressure-sensitive adhesive layer (b) or pressure-sensitive adhesive layer (d), separating by heating the processed adherend from the reinforcing plate together with, adherent thereto, the substrate (a) having the pressure-sensitive adhesive layer (c) while supporting the processed adherend with a support, and further separating the processed adherend from the substrate (a) having the pressure-sensitive adhesive layer (c) while keeping the adherend in the state of being supported by the support.

10. **(withdrawn):** The method of processing an adherend according to claim 8, wherein the adhesion of the adherend and/or the reinforcing plate to the given surface of the heat-peelable double-faced pressure-sensitive adhesive sheet is conducted under reduced pressure.

11. **(withdrawn):** The method of processing an adherend according to claim 8, wherein a heating and pressing treatment is conducted after the adherend and/or reinforcing plate is adhered to the given surface of the heat-peelable double-faced pressure-sensitive adhesive sheet.

**12. (withdrawn):** The method of processing an adherend according to claim 8, wherein the adherend is an electronic part or an analogue thereof.

**13. (withdrawn):** The method of processing an adherend according to claim 8, wherein the reinforcing plate to which the heat-peelable pressure-sensitive adhesive layer (b) and the pressure-sensitive adhesive layer (d) are adherent and which is obtained by causing separation at the interface between the heat-peelable pressure-sensitive adhesive layer (b) and the substrate (a) by heating is separated from the heat-peelable pressure-sensitive adhesive layer (b) and the pressure-sensitive adhesive layer (d) using a sheet or tape for peeling to thereby recover the reinforcing plate and this reinforcing plate recovered is reused in the processing of another adherend.

**14. (original):** An electronic part, which is produced with the heat-peelable double-faced pressure-sensitive adhesive sheet according to claims 1 to 3.

**15. (currently amended):** An electronic part, which is produced by utilizing the method of processing an adherend using the heat-peelable double-faced pressure-sensitive adhesive sheet according to any one of claims 1 to 3, wherein said method comprises adhering the adherend to the surface of the pressure-sensitive adhesive layer (c) in the heat-peelable double-faced pressure-sensitive adhesive sheet, adhering a reinforcing plate to the surface of the heat-peelable pressure-sensitive adhesive layer (b) or pressure-sensitive adhesive layer (d), processing the adherend, subsequently causing separation at the interface between the heat-peelable pressure-sensitive adhesive layer (b) and the substrate (a) by heating, separating the processed adherend from the reinforcing plate together with, adherent thereto, the substrate (a)

having the pressure-sensitive adhesive layer (c), and further separating the processed adherend from the substrate (a) having the pressure-sensitive adhesive layer (c) according to claim 8.